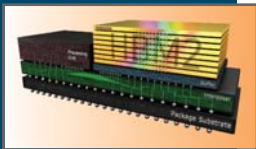
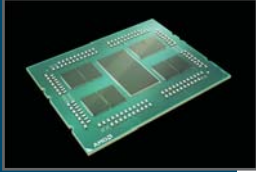


Advanced Packaging Update: Market and Technology Trends

Vol. 3-1119



This issue of the Advanced Packaging Update features special coverage of outsourced semiconductor assembly and test (OSAT) financials for the first half of 2019. A section on the use of chiplets is provided and new versions of embedded bridge technology are discussed. High bandwidth memory developments, including an analysis of supply and demand is provided. A market forecast for HBM is included. The report also examines Apple's new iPhone 11 with a discussion of the increased use of underfill.

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Annual subscription – \$5,100 (4 issues)
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TechSearch
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4801 Spicewood Springs Road • Suite 150
Austin, Texas 78759
Tel: 512-372-8887 • Fax: 512-372-8889
tsi@techsearchinc.com • www.techsearchinc.com